



Automatic Lager Area Bond Tester 8600C

Bond System

Testheads Pullheads – 100cN, 1000cN, 5000cN
Shearheads – 500cN, 5000cN

Machine Base

Mechanics

Table travel axis travel: approx.: x= 720 mm y=512 mm
X, Y, Z Resolution 1 µm, repeatability 5 µm
Speed All axes programmable from 0.2 to 16 mm/s
Test speed from 0.2 to 5mm/s

Measurement heads

Accuracy 0.25% of maximum value
Calibration Stored in measurement head, temperature-
Compensated load cell
Optional calibration at customers side
(specific tools)

Control

Computer Dual Core PC, Ethernet, USB 2.0/3.0
GigE-CCD-Colour Camera,
fully networkable in TCP/IP server

Monitor TFT flat screen monitor 22"

Operating system Windows 10

Printer all Windows-compatible printers can be
installed

8600C:

The automatic large area bond tester 8600C complements F&S Bondtec Semiconductor GmbH die- and wire- bonders.

The PC controlled moving axis allows any number of bonds to be tested automatically from a stored program on a large area (eg. for Battery-, Solar-application,...).

Results can be analysed and output immediately or exported in a number of data base formats for subsequent analysis as desired.

Powerful extended capabilities enable measurements such as force/time curves to be made and deliver more data about the quality of the bond tested.

Exchangeable measurement cartridges ensure rapid conversion to different force ranges. The calibration curves of all measurement cartridges are stored internally; additional heads for shear, and tweezer testing with customer-specific tools and jaws are available.

After a first programming a reproducible pull- or shear-test can be guaranteed for all following components.

Additional features

Programming	Automatic repeat measurements on hybrids or COB using the programmable head movement and Pattern Recognition Unit (PRU)
Evaluation	Statistics such as mean value, standard deviation, trend, cpk, etc. Based on SQL Databank
Export format	SQL, CSV, HTML
Other	Operator profile, various password levels, optional barcode readers for product Identification; feedback of measured values to die and wire bonders for parameter optimisation optional

General

Microscope	Stereoscope Olympus, other microscopes optional
Lighting	LED spot light
Dimensions	approx. height 200cm, width 130cm, depth 100cm, approx. 600kg
Supplies	a100-240 VAC,
Connections	Air 6 bar; vacuum 0,7 bar

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